

ABSTRACT

The application provides a die-bonding machine, including: a transferring unit used to support and transfer a substrate to a bonding position; a feeding unit used to position and supply the substrate to the transferring unit; a die supply unit used to support a die ring and supply dies to a die supply position; a die ring supply unit used to supply full die rings to the die supply unit and recover empty die rings in the die supply unit; a turret mechanism for transferring the dies in the die supply position to a die extraction position; a piercing mechanism for downwardly piercing a blue film of a die on the die supply position to push the die to the turret mechanism; and, and a die-bonding mechanism. The die-bonding machine provided by this application can realize the automatic supply and fixed-point movement of the substrate; in addition, it can realize the automatic supply and recovery of the die ring, and the piercing mechanism pierces the blue film downward to peel the die to the turtle mechanism, and transfer to the die extraction position for the die-bonding mechanism, which can avoid the failure of die extraction, shorten the stroke and time of the die-bonding mechanism to move the die, improving the stability of the die movement, the bonding accuracy and bonding efficiency.

FIG. 2